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Semiconductor devices - Mechanical and climatic test methods - Part 22-2: Bond strength - Wire bond shear test methods

Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques - Partie 22-2: Robustesse des contacts soudés - Méthodes d'essais de cisaillement des contacts soudés par fil

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FOREWORD

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This International Standard is to be used in conjunction with IEC 60749-22-1:2025.

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This edition includes the following significant technical changes with respect to the previous edition:

a) Major update, including new techniques and use of new materials (e.g. copper wire) involving a complete rewrite as two separate subparts (this document and IEC 60749-22-1).

The text of this International Standard is based on the following documents:

Draft	Report on voting
47/2959/FDIS	47/2981/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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